**SUGGESTED U.S. MANUFACTURING PLAN TEMPLATE**

Instructions

The Applicant may use this template to provide the required one-page U.S. Manufacturing Plan as part of the Full Application. The Applicant may use its own format for the one-page U.S. Manufacturing Plan as long as the Applicant’s format includes the required statements, baseline requirements, and any required additional details.

This U.S. Manufacturing Plan will be reviewed and, if the Applicant is selected for an award, incorporated into the final Attachment 2 – Intellectual Property Provisions of the award cooperative agreement. Applicant may be contacted to negotiate revisions to the submitted U.S. Manufacturing Plan prior to any award or while negotiating Attachment 2 if the Applicant is selected for an award.

Please do not submit confidential business information (trade secrets, commercial or financial information that is privileged or confidential) in the U.S. Manufacturing Plan unless that information is critical for the evaluation of the U.S. Manufacturing Plan. If the U.S. Manufacturing Plan must include any confidential business information, please include the following statement on a cover page and indicate in the margins which paragraphs contain the confidential business information:

***NOTICE OF RESTRICTION ON DISCLOSURE AND USE OF DATA***

*Paragraph(s) [\_\_] of this document are marked as containing trade secrets or commercial or financial information that is privileged or confidential and exempt from public disclosure. Such information shall be used or disclosed only for evaluation purposes or in accordance with a financial assistance or loan agreement between the submitter and the Government. The Government may use or disclose any information that is not appropriately marked or otherwise restricted, regardless of source.*

Any information not marked as above will be considered appropriate for public release.

Project Title

Project Control Number

Principal Investigator Name

Date

**[APPLICANT]** U.S. Manufacturing Plan

If selected for funding, the Applicant agrees to the following commitments as a condition of that funding:

1. **[APPLICANT]** agrees that any products embodying any subject invention or produced through the use of any subject invention will be manufactured substantially in the United States for any use or sale anywhere in the world, including by **[APPLICANT]**’s assignees, exclusive or non-exclusive licensees, and by entities which may acquire a controlling interest in **[APPLICANT]**.
2. Additional Details: In addition to the above, **[APPLICANT]** agrees to **[provide one or more specific and measurable commitments.]**